

# MPSW01 NPN General Purpose Amplifier

### **Features**

- This device is designed for general purpose medium power amplifiers
- · Sourced from process 37



## Absolute Maximum Ratings \* Ta = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
VCEO	Collector-Emitter Voltage	30	V
Vсво	Collector-Base Voltage	40	V
VEBO	Emitter-Base Voltage	5.0	V
Ic	Collector Current - Continuous	1.0	А
P <sub>D</sub>	Total Device Dissipation Derate about 25°C	1.0 8.0	W mW/°C
$T_{J}$ , $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

#### Note:

## **Thermal Characteristics**

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case*	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambien*	125	°C/W

<sup>\*</sup> Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6cm<sup>2</sup>

<sup>1)</sup> These ratings are based on a maximum junction temperature 150 'C

<sup>2)</sup> These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

## Electrical Characteristics (Note) T<sub>a</sub> = 25°C unless otherwise noted

**Parameter** 

Off Characteristics					
V <sub>(BR)</sub> CEO	Collector-Emitter Breakdown Voltage	Ic = 10 mA, I <sub>B</sub> = 0	30		V
V <sub>(BR)</sub> CBO	Collector-Base Breakdown Voltage	Ic = 100 uA, IE = 0	40		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	IE = 100 uA, Ic = 0	5.0		V
Ісво	Collector-Cutoff Current	Vcb = 30 V, IE = 0		0.1	uA
<b>І</b> ЕВО	Emitter-Cutoff Current	V <sub>EB</sub> = 3.0 V, I <sub>C</sub> = 0		0.1	uA

**Test Condition** 

### On Characteristics

**Symbol** 

hfE	DC Current Gain	Ic = 10 mA, VcE = 1.0 V Ic = 100 mA, VcE = 1.0 V Ic = 1.0 A, VcE = 1.0 V	55 60 50		
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage *	Ic = 1.0A, I <sub>B</sub> = 100 mA		0.5	V
V <sub>BE(on)</sub>	Emitter-Base On Voltage *	Ic = 1.0A, VcE = 1.0 V		1.2	V

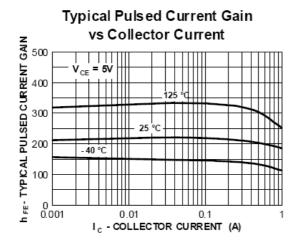
### **Small Signal Characteristics**

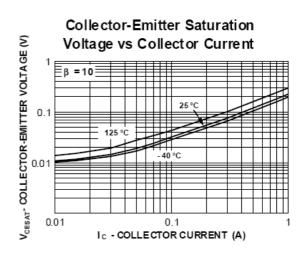
f⊤	Small-Signal Current Gain	Ic = 50 mA, VcE = 10 V, f = 20 MHz	50		MHz
Ccb	Collector-Base Capacitance	VcB = 10 V, IE = 0, f = 1.0 MHz		20	pF

#### Note:

- 1) These ratings are based on a maximum junction temperature 150 'C
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations
- 3) \*Pulse Test: Pulse Width≤300µs, Duty Cycle≤1.0%

## **Typical Characteristics**



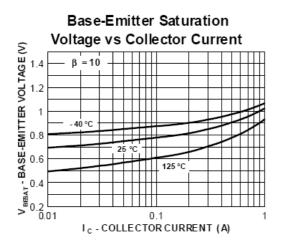


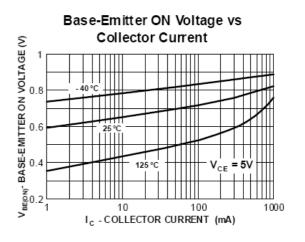
MIN

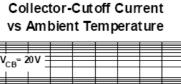
**MAX** 

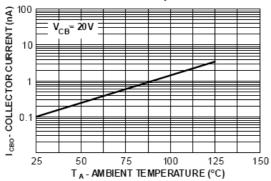
Units

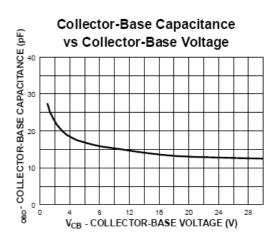
## Typical Characteristics (continued)

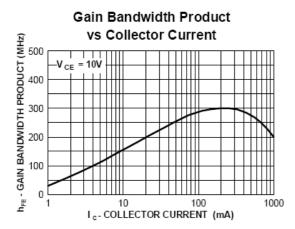


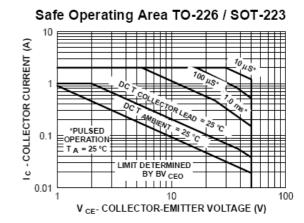




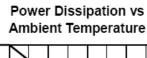


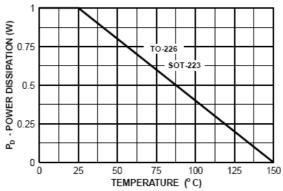






## Typical Characteristics (continued)





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